NONPROVISIONAL PATENT **APPLICATION TRANSMITTAL RULE §1.53(b)** IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Docket No.

025796-00014

1050 Connecticut Avenue, N.W.,

Date:

December 15, 2003

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ARENT FOX KINTNER PLOTKIN & KAHN, PLLC

Director of the U.S. PTO Washington, D.C. 20231

Customer No. 004372

Sir:

Transmitted herewith for filing under 37 C.F.R. §1.53(b) is a nonprovisional patent application:

For (Title):

HIGH-DENSITY MULTICHIP MODULE PACKAGE

By (Inventors):

Kwun Yao HO (Taiwan, Republic of Korea) and Moriss KUNG (Taiwan,

Republic of Korea)

- 14 pages of Specification/Claims 1-24/Abstract are attached.
- Formal drawings (Fig(s). 1-7; 5 sheet(s)) is/are attached.
- A Declaration and Power of Attorney is attached.
- An assignment of the invention to VIA Technologies, Inc. is attached, along with Form PTO-1595 and a check for \$40.00.
- \boxtimes Priority of foreign application No. 091136733 filed December 19, 2003 in Republic of China is claimed under 35 U.S.C. §119.
- \boxtimes A certified copy of the above corresponding foreign application is attached.

The filing fee is calculated below and includes claim status after entry of any Preliminary Amendment noted above:

FOR:	NO. FILED	NO. EXTRA
BASIC FEE		
TOTAL CLAIMS	24 - 20	= 4
INDEP CLAIMS	2 - 3	= 0
☐ MULTIPLE DEPENDENT CLAIMS		

RATE	FEE	
	\$ 385	
x 9 =	\$	
x 43 =	\$	

SMALL ENTITY

<u>OR</u> <u>OR</u> OR

<u>OR</u>

<u>OR</u>

<u>OR</u>

\$ **TOTAL**

\$

RATE	FEE
	\$ 770
x 18	\$ 72
x 86	\$0
+290	\$

\$842

TOTAL

LARGE ENTITY

冈 A check in the amount of \$882 (\$842 for the filing fee and \$40 for the Assignment Recordation Fee) is attached. Please charge any fee deficiency or credit any overpayment to Deposit Account No. 01-2300.

Respectfully submitted,

+145 =

Raymond J. Ho

Registration No. 41,838

RJH/rkc